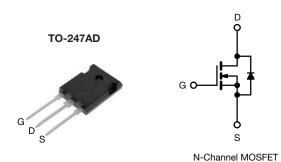
Vishay Siliconix

E Series Power MOSFET

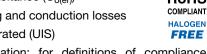


| PRODUCT SUMMARY | | | | | |
|--|------------------------------|--|--|--|--|
| V _{DS} (V) at T _J max. | 850 | | | | |
| R _{DS(on)} typ. (Ω) at 25 °C | V _{GS} = 10 V 0.205 | | | | |
| Q _g max. (nC) | 72 | | | | |
| Q _{gs} (nC) | 9 | | | | |
| Q _{gd} (nC) | 22 | | | | |
| Configuration | Single | | | | |

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)

 Material categorization: for definitions of compliance please see www.vishav.com/doc?99912



APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

| ORDERING INFORMATION | | | | |
|---------------------------------|-----------------|--|--|--|
| Package | TO-247AD | | | |
| Lead (Pb)-free and halogen-free | SiHW21N80AE-GE3 | | | |

| ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted) | | | | | | |
|--|-------------------------|---|-----------------------------------|-------------|------|--|
| PARAMETER | | | SYMBOL | LIMIT | UNIT | |
| Drain-source voltage | | | V _{DS} | 800 | ., | |
| Gate-source voltage | | | V _{GS} | ± 30 | V | |
| Continuous drain current (T _J = 150 °C) | V _{GS} at 10 V | $T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$ | - I _D | 17.4 | A | |
| | V _{GS} at 10 V | T _C = 100 °C | | 11 | | |
| Pulsed drain current ^a | | | I _{DM} | 38 | | |
| Linear derating factor | | | | 1.4 | W/°C | |
| Single pulse avalanche energy b | | | E _{AS} | 127 | mJ | |
| Maximum power dissipation | | | P _D | 179 | W | |
| Operating junction and storage temperature range | | | T _J , T _{stg} | -55 to +150 | °C | |
| Drain-source voltage slope $T_J = 125 ^{\circ}\text{C}$ | | | dv/dt | 70 | V/ns | |
| Reverse diode dv/dt ^d | | | | 39 | | |
| Soldering recommendations (peak temperature) c For 10 s | | | | 260 | °C | |

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 1.5 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, di/dt = 100 A/ μ s, starting $T_J = 25$ °C



Vishay Siliconix

| THERMAL RESISTANCE RATINGS | | | | | | |
|----------------------------------|-------------------|------|------|------|--|--|
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT | | |
| Maximum junction-to-ambient | R _{thJA} | = | 40 | °C/W | | |
| Maximum junction-to-case (drain) | R _{thJC} | - | 0.7 | C/VV | | |

| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
|---|-----------------------|---|---|------|-------|-------|------|
| Static | | • | | | • | • | |
| Drain-source breakdown voltage | V _{DS} | V _{GS} = | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ | | - | - | V |
| V _{DS} temperature coefficient | $\Delta V_{DS}/T_{J}$ | Referenc | e to 25 °C, I _D = 1 mA | - | 0.8 | - | V/°C |
| Gate-source threshold voltage (N) | V _{GS(th)} | V _{DS} = | V _{GS} , I _D = 250 μA | 2.0 | - | 4.0 | V |
| | | , | $V_{GS} = \pm 20 \text{ V}$ | | - | ± 100 | nA |
| Gate-source leakage | I _{GSS} | , | V _{GS} = ± 30 V | | - | ± 1 | μΑ |
| 7 | | V _{DS} = | $V_{DS} = 800 \text{ V}, V_{GS} = 0 \text{ V}$ | | - | 1 | |
| Zero gate voltage drain current | I _{DSS} | V _{DS} = 640 V | , V _{GS} = 0 V, T _J = 125 °C | - | - | 10 | μA |
| Drain-source on-state resistance | R _{DS(on)} | V _{GS} = 10 V | I _D = 11 A | - | 0.205 | 0.235 | Ω |
| Forward transconductance a | 9 _{fs} | V _{DS} | = 30 V, I _D = 3 A | - | 4.0 | - | S |
| Dynamic | | | | • | • | • | |
| Input capacitance | C _{iss} | | V _{GS} = 0 V, | - | 1388 | - | - |
| Output capacitance | C _{oss} | , | $V_{DS} = 100 \text{ V},$ | - | 53 | - | |
| Reverse transfer capacitance | C _{rss} | 1 | f = 1 MHz | | 5 | - | pF |
| Effective output capacitance, energy related ^a | $C_{o(er)}$ | | V _{DS} = 0 V to 480 V, V _{GS} = 0 V | | 43 | - | |
| Effective output capacitance, time related ^b | C _{o(tr)} | V _{DS} = 0 \ | | | 276 | - | |
| Total gate charge | Qg | | | - | 48 | 72 | |
| Gate-source charge | Q _{gs} | V _{GS} = 10 V | V _{GS} = 10 V | | 9 | - | nC |
| Gate-drain charge | Q _{gd} | | | - | 22 | - | |
| Turn-on delay time | t _{d(on)} | | | - | 21 | 42 | |
| Rise time | t _r | V _{DD} = | V _{DD} = 640 V, I _D = 11 A, | | 38 | 76 | |
| Turn-off delay time | t _{d(off)} | V _{GS} = | = 10 V, $R_g = 20 \Omega$ | - | 71 | 107 | ns |
| Fall time | t _f | | | - | 76 | 114 | |
| Gate input resistance | R_g | f = 1 | f = 1 MHz, open drain | | 0.55 | 1.1 | Ω |
| Drain-Source Body Diode Characteristic | s | | | | | | |
| Continuous source-drain diode current | I _S | MOSFET symbol showing the integral reverse p - n junction diode | | - | - | 17.4 | _ |
| Pulsed diode forward current | I _{SM} | | | - | - | 38 | A |
| Diode forward voltage | V _{SD} | T _J = 25 °C, I _S = 11 A, V _{GS} = 0 V | | - | - | 1.2 | V |
| Reverse recovery time | t _{rr} | $T_J = 25 \text{ °C}, I_F = I_S = 11 \text{ A},$ $di/dt = 100 \text{ A/}\mu\text{s}, V_R = 25 \text{ V}$ | | - | 400 | 800 | ns |
| Reverse recovery charge | Q _{rr} | | | - | 5 | 10 | μC |
| Reverse recovery current | I _{RRM} | | | - | 20 | - | A |

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

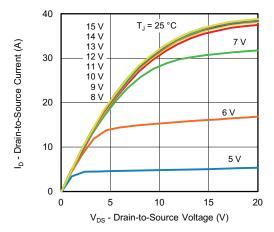


Fig. 1 - Typical Output Characteristics

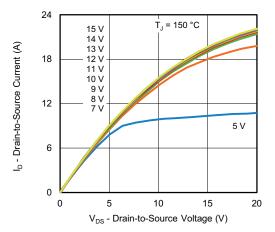


Fig. 2 - Typical Output Characteristics

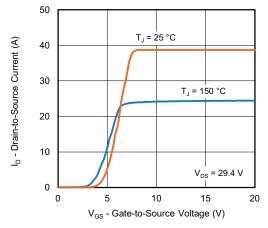


Fig. 3 - Typical Transfer Characteristics

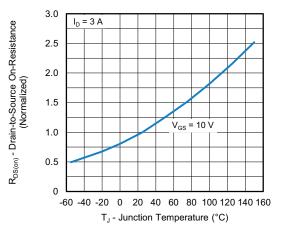


Fig. 4 - Normalized On-Resistance vs. Temperature

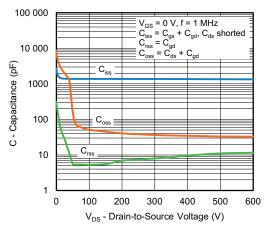


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

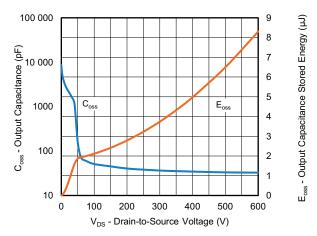


Fig. 6 - Coss and Eoss vs. VDS



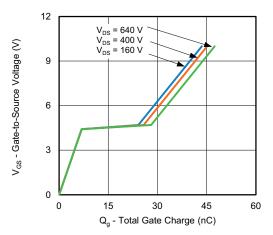


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

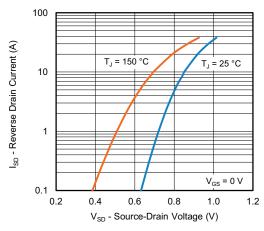


Fig. 8 - Typical Source-Drain Diode Forward Voltage

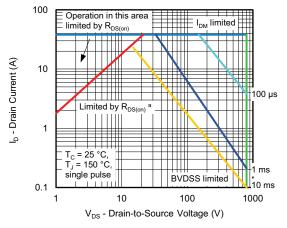


Fig. 9 - Maximum Safe Operating Area



a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

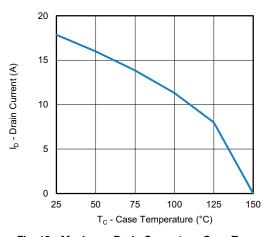


Fig. 10 - Maximum Drain Current vs. Case Temperature

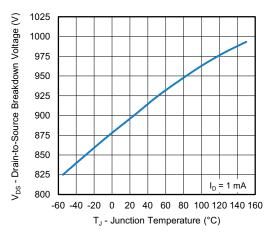


Fig. 11 - Temperature vs. Drain-to-Source Voltage



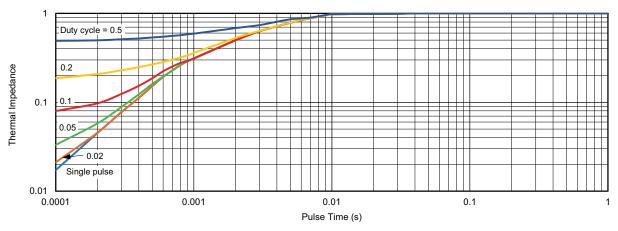


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

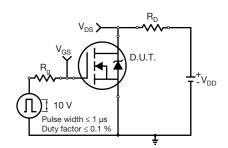


Fig. 13 - Switching Time Test Circuit

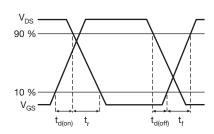


Fig. 14 - Switching Time Waveforms

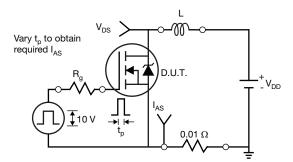


Fig. 15 - Unclamped Inductive Test Circuit

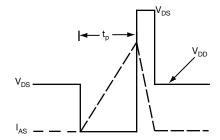


Fig. 16 - Unclamped Inductive Waveforms

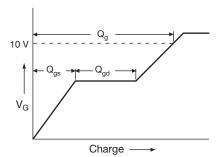


Fig. 17 - Basic Gate Charge Waveform

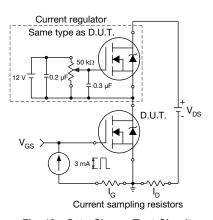
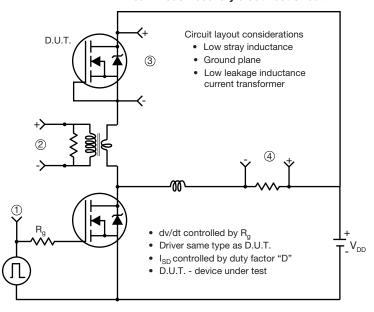


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



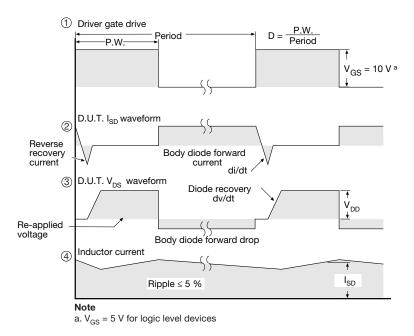
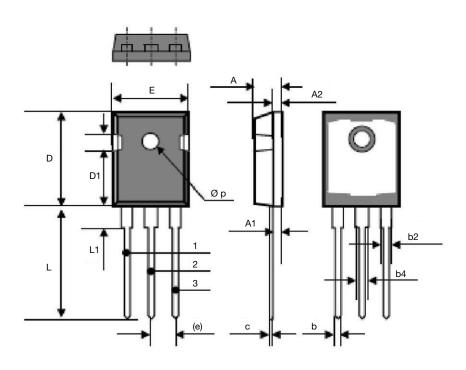


Fig. 19 - For N-Channel

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Vishay Siliconix

TO-247AD (High Voltage)



| DIM. | MILLII | METERS | INCHES | | |
|-------------------------|-----------|--------|-----------|-------|--|
| | MIN. | MAX. | MIN. | MAX. | |
| Α | 4.70 | 5.31 | 0.185 | 0.209 | |
| A1 | 2.21 | 2.59 | 0.087 | 0.102 | |
| A2 | 1.50 | 2.49 | 0.059 | 0.098 | |
| b | 0.99 | 1.40 | 0.039 | 0.055 | |
| b2 | 1.65 | 2.41 | 0.065 | 0.095 | |
| b4 | 2.59 | 3.43 | 0.102 | 0.135 | |
| С | 0.61 BSC | | 0.024 BSC | | |
| D | 20.80 | 21.46 | 0.819 | 0.845 | |
| D1 | 3.68 | 5.49 | 0.145 | 0.216 | |
| (e) | 5.46 BSC | | 0.215 BSC | | |
| Е | 15.49 | 16.26 | 0.610 | 0.640 | |
| L | 19.81 | 20.32 | 0.780 | 0.800 | |
| L1 | 4.06 | 4.50 | 0.160 | 0.177 | |
| Øp | 3.51 | 3.66 | 0.138 | 0.144 | |
| ECN: S17-0178-Rev. B, 0 | 06-Feb-17 | • | • | | |

ECN: S17-U178-Rev. B, U6-Feb-17

DWG: 6010



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